



### Layer Counts:

- Single-Layer : IPC 6013, MIL-P-50884 - Type 1
- Double-Layer : IPC 6013, MIL-P-50884 - Type 2
- Multi-Layer : IPC 6013, MIL-P-50884 - Type 3
- Rigid-Flex : IPC 6013, MIL-P-50884 - Type 4
- Multi-Layer (not plated through) :  
IPC 6013, MIL-P-50884 - Type 5

### Materials:

- Polyimide (Kapton), Dupont FR & LF
- Adhesive and Adhesiveless materials
- FR-4, high Tg, high Td, CAF resistant & Halogen-free
- Teflon, PTFE

Cover/substrate: Polyimide film: 1 mil (25 $\mu$ m)\*, 2 mil (50 $\mu$ m)\*, 3 mil (75 $\mu$ m), 5 mil (125 $\mu$ m); Photoimageable

### Conductors:

- Copper: 1/8 oz. (5 $\mu$ m), 1/4 oz. (9 $\mu$ m), 1/3 oz. (12 $\mu$ m), 1/2 oz. (18 $\mu$ m)\*, 1 oz. (35 $\mu$ m)\*, 2 oz. (71 $\mu$ m)
- Nickel: 2 mil (50 $\mu$ m), 5 mil (125 $\mu$ m)
- Silver-screened conductors
- Silver Film conductors

### Stiffeners:

- FR-4, Polyimide, Polyimide tape
- Thermoset and Pressure application

### Quality:

- IPC-6013 Class 2
- ISO-9001:2008 Registered
- RoHS Compliant
- UL Certified (94-V0)
- Complete analytical capabilities

### Quality

#### Piyush Patel

Quality Manager

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### Engineering

#### Ari Seevaratanum

CAM Engineer

Email: ValueEngineering@Customers.com

- \* 100% Net List Electrical test
- \* JIT delivery
- \* Turn-key assembly
- \* Fast Turn Around:

- Prototypes: 2 days
- Production: 5 days

### Technology:

- Wire bondable gold plating
- Soft/Hard gold plating
- PIC (Photoimageable Coverlay)
- Automatic and Hand Crafted assembly
- Laser cutting and skiving
- Turnkey packaging solutions
- Engineering design services



UL Approved